

## PCN# 20180628002.1 Qualification of MIHO8 as an additional Fab site option for select ABCD5HV devices Change Notification / Sample Request

Date: July 03, 2018 To: TOKYO ELECTRON DEVICE (DSTR) PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

We request you acknowledge receipt of this notification within **30** days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance of the change. If you require samples or additional data to support your evaluation, please request within 30 days.

The changes discussed within this PCN will not take effect any earlier than **90** days from the date of this notification, unless customer agreement has been reached on an earlier implementation of the change. This notification period is per TI's standard process.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Manager (<u>PCN ww admin team@list.ti.com</u>).

PCN Team SC Business Services

## 20180628002.1 Attachment: 1

## **Products Affected:**

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

### DEVICE

## **CUSTOMER PART NUMBER**

TCAN1042HVDR TCAN1042HD TCAN1042HDR TCAN1042HGD TCAN1051HGD

null
null
null
null
null

Technical details of this Product Change follow on the next page(s).

PCN Numb	ber:	2018	0628002.1	P	<b>CN Date</b>	: Ju	ıly 3, 2018
Title: Qualification of MIHO8 as an additional Fab site option for select ABCD5HV devices							
Customer Contact:				Estimate			ate provided at
Proposed 1 <sup>st</sup> Ship Date:		ate:	Oct 3, 2018 Availa				ample request.
Change Ty	ype:						
Assembly Site		[	Assembly Pro			Assembly Materials	
Design			Electrical Spe			Mechanical Specification	
Test S			Packing/Ship	Test Process			
	Bump Site		Wafer Bump Material				Bump Process
🛛 Wafer	Wafer Fab Site Wafer Fab Materials Wafer Fab Process   Part number change Vafer Fab Process				Fab Process		
		[ [		Details			
Descriptio	on of Chan	<b>7</b> 0'	PCN	Details			
			announce the qu	alification of its	MIHO8 fa	abricat	ion facility as an
additional \	Wafer Fab s	source for	the selected devi	ces listed in the	"Product	Affect	ed" section.
	-						
		nt Fab Sit			dditiona		
Current		rocess	Wafer Diameter	Additional	Proc	ess	Wafer
Site MAINEF		BCD5HV	200 mm	Fab Site MIHO8	ABCD	541/	Diameter 200 mm
MAINLI		JCDJIIV	200 11111	MINUO	ADCD	JIIV	200 11111
Continuity			Qual Data Sectio		bility (po	ositive	e / negative):
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## **Qualification Report**

# ABCD05HV in Miho8 Approve Date 23-Jun-2018

#### **Product Attributes**

Attributes	Qual Device: TCAN1042HVDRQ1	Qual Device: TCAN1051VDRQ1
Assembly Site	FMX	FMX
Package Family	SOIC	SOIC
Flammability Rating	UL 94 V-0	UL 94 V-0
Wafer Fab Supplier	MIHO8	MIHO8
Wafer Fab Process	ABCD05HV.3	ABCD05HV.3

- QBS: Qual By Similarity

- Qual Devices TCAN1042HVDRQ1 and TCAN1051VDRQ1 are qualified at LEVEL1-260C

Qualification Results Data Displayed as: Number of lots / Total sample size / Total failed				
Туре	Test Name / Condition	Duration	Qual Device: TCAN1042HVDRQ1	Qual Device: TCAN1051VDRQ1
AC	Autoclave 121C	96 Hours	2/154/0	1/77/0
CDM	ESD - CDM	1500 V	2/6/0	1/3/0
ED	Electrical Distributions	Per Datasheet Parameters	3/90/0	3/90/0
ELFR	Early Life Failure Rate, 125C	48 Hours	2/1600/0	1/800/0
HAST	Biased HAST, 130C/85%RH	96 Hours	2/154/0	1/77/0
нвм	ESD - HBM	6000 V	1/3/0	1/3/0
нвм	ESD - HBM (Bus Pins Only)	16000 V	2/6/0	1/3/0
HTOL	Life Test, 150C	300 Hours	2/153/0	1/77/0
HTSL	High Temp Storage Bake 175C	500 Hours	2/90/0	1/45/0
LU	Latch-up	(Per JESD78)	2/12/0	1/6/0
тс	Temperature Cycle, -65/150C	500 Cycles	2/154/0	1/77/0
WBP	Bond Pull	Wires	2/60/0	-
WBS	Wire Bond Shear	Wires	2/60/0	1/30/0

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

- The following are equivalent HTOL options based on an activation energy of 0.7eV: 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

- The following are equivalent HTSL options based on an activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours

- The following are equivalent Temp Cycle options per JESD47: -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

Green/Pb-free Status:

Qualified Pb-Free (SMT) and Green

THIS INFORMATION RELATING TO QUALITY AND RELIABILITY IS PROVIDED "AS IS." Product information detailed in this report may not accurately reflect TI's current product materials, processes and testing used in the construction of the TI products. Customers are solely responsible to conduct sufficient engineering and additional qualification testing to determine whether a device is suitable for use in their applications. Using TI products outside limits stated in TI's datasheet may void TI's warranty. See TI's Terms of Sale at <a href="http://www.ti.com/Isds/ti/leqal/terms.org">http://www.ti.com/Isds/ti/leqal/terms.org</a>

For questions regarding this notice, e-mails can be sent to the regional contacts shown below, or you can contact your local Field Sales Representative.

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